SN5433, SN54LS33, SN7433, SN74LS33
QUADRUPLE 2-INPUT POSITIVE-NOR BUFFERS WITH OPEN-COLLECTOR OUTPUTS

SDLS101

DECEMBER 1983—REVISED MARCH 1988

- **Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs**
- **Dependable Texas Instruments Quality and Reliability**

description

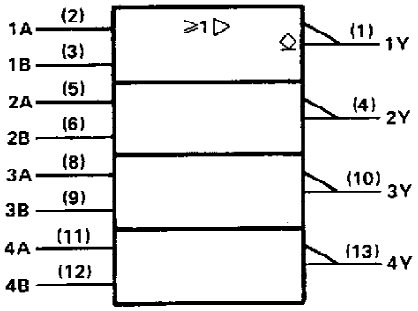
These devices contain four independent 2-input NOR buffer gates with open-collector outputs. Open-collector outputs require resistive pull-up to perform logically but can deliver higher V_{OH} levels and are commonly used in wired-AND applications.

The SN5433 and SN54LS33 are characterized for operation over the full military temperature range of −55°C to 125°C. The SN7433, and SN74LS33 are characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each gate)

INPUTS		OUTPUT
A	B	Y
H	X	L
X	H	L
L	L	H

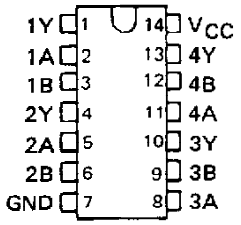
logic symbol†



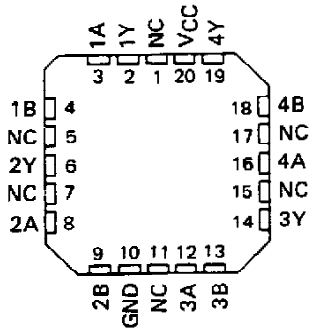
† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

SN5433, SN54LS33 . . . J OR W PACKAGE
SN7433 . . . N PACKAGE
SN74LS33 . . . D OR N PACKAGE
(TOP VIEW)

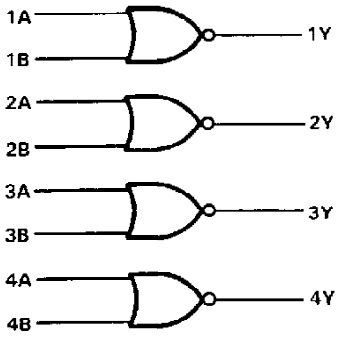


SN54LS33 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

logic diagram

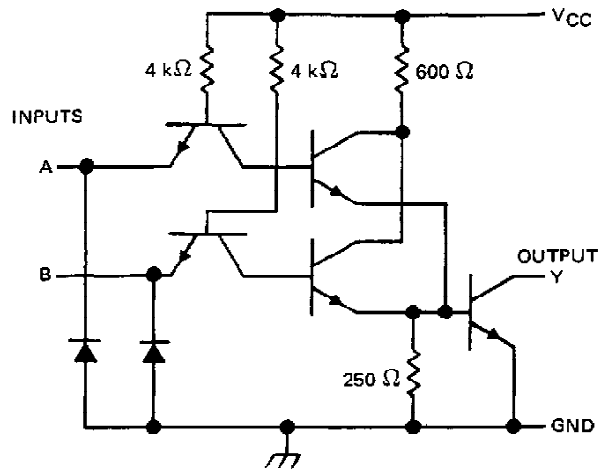


positive logic

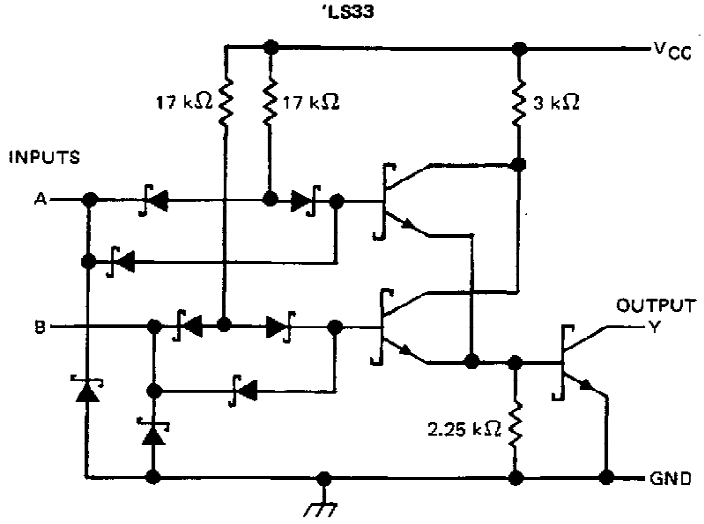
$$Y = \overline{A + B} \text{ or } Y = \overline{A} \cdot \overline{B}$$

schematics (each gate)

'33



'LS33



Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage: '33	5.5 V
'LS33	7 V
Off-state output voltage	7 V
Operating free-air temperature: SN54'	–55°C to 125°C
SN74'	0°C to 70°C
Storage temperature range	–65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN5433			SN7433			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
V_{OH}	High-level output voltage			5.5			5.5	V
I_{OL}	Low-level output current			48			48	mA
T_A	Operating free-air temperature	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN5433			SN7433			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	V_{CC} = MIN, I_I = −12 mA			−1.5			−1.5	V
I_{OH}	V_{CC} = MIN, V_{IL} = 0.8 V, V_{OH} = 5.5 V						0.25	mA
	V_{CC} = MIN, V_{IL} = 0.7 V, V_{OH} = 5.5 V			0.25				
V_{OL}	V_{CC} = MIN, V_{IH} = 2 V, I_{OL} = 16 mA		0.2	0.4		0.2	0.4	V
I_I	V_{CC} = MAX, V_I = 5.5 V			1			1	mA
I_{IH}	V_{CC} = MAX, V_I = 2.4 V			40			40	μA
I_{IL}	V_{CC} = MAX, V_I = 0.4 V			−1.6			−1.6	mA
I_{CCH}	V_{CC} = MAX, V_I = 0		3	6		3	6	mA
I_{CCL}	V_{CC} = MAX, See Note 2		9	16.5		9	16.5	mA

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡All typical values are at V_{CC} = 5 V, T_A = 25°C.
NOTE 2: One input at 4.5 V, all others at 0 V.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	A or B	Y	R_L = 133 kΩ, C_L = 50 pF		10	15	ns
t_{PHL}					12	18	ns
t_{PLH}			R_L = 133 kΩ, C_L = 150 pF		15	22	ns
t_{PHL}					16	24	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

recommended operating conditions

		SN54LS33			SN74LS33			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.7			0.8	V
V_{OH}	High-level output voltage			5.5			5.5	V
I_{OL}	Low-level output current			12			24	mA
T_A	Operating free-air temperature	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†				SN54LS33			SN74LS33			UNIT
					MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	V_{CC} = MIN,	I_I = −18 mA					−1.5			−1.5	V
I_{OH}	V_{CC} = MIN,	V_{IH} = 2 V,	V_{IL} = MAX,	V_{OH} = 5.5 V			0.25			0.25	mA
V_{OL}	V_{CC} = MIN,	V_{IH} = 2 V,	V_{IL} = MAX,	I_{OL} = 12 mA		0.25	0.4		0.25	0.4	V
	V_{CC} = MIN,	V_{IL} = MAX,	I_{OL} = 24 mA						0.35	0.5	
I_I	V_{CC} = MAX,	V_I = 7 V					0.1			0.1	mA
I_{IH}	V_{CC} = MAX,	V_I = 2.7 V					20			20	μA
I_{IL}	V_{CC} = MAX,	V_I = 0.4 V					−0.4			−0.4	mA
I_{CCH}	V_{CC} = MAX,	V_I = 0				1.8	3.6		1.8	3.6	mA
I_{CCL}	V_{CC} = MAX,	See Note 2				6.9	13.8		6.9	13.8	mA

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡All typical values are at V_{CC} = 5 V, T_A = 25°C.
NOTE 2: One input at 4.5 V, all others at 0 V.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_{PLH}	A or B	Y	R_L = 667 Ω,	C_L = 45 pF		20	32	ns
t_{PHL}						18	28	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
8512601CA	Active	Production	CDIP (J) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8512601CA SNJ54LS33J
8512601DA	Active	Production	CFP (W) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8512601DA SNJ54LS33W
SN54LS33J	Active	Production	CDIP (J) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54LS33J
SN54LS33J.A	Active	Production	CDIP (J) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54LS33J
SN74LS33D	Obsolete	Production	SOIC (D) | 14	-	-	Call TI	Call TI	0 to 70	LS33
SN74LS33DR	Active	Production	SOIC (D) | 14	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS33
SN74LS33DR.A	Active	Production	SOIC (D) | 14	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS33
SN74LS33N	Active	Production	PDIP (N) | 14	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS33N
SN74LS33N.A	Active	Production	PDIP (N) | 14	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS33N
SN74LS33NSR	Active	Production	SOP (NS) | 14	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS33
SN74LS33NSR.A	Active	Production	SOP (NS) | 14	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS33
SNJ54LS33J	Active	Production	CDIP (J) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8512601CA SNJ54LS33J
SNJ54LS33J.A	Active	Production	CDIP (J) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8512601CA SNJ54LS33J
SNJ54LS33W	Active	Production	CFP (W) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8512601DA SNJ54LS33W
SNJ54LS33W.A	Active	Production	CFP (W) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8512601DA SNJ54LS33W

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54LS33, SN74LS33 :

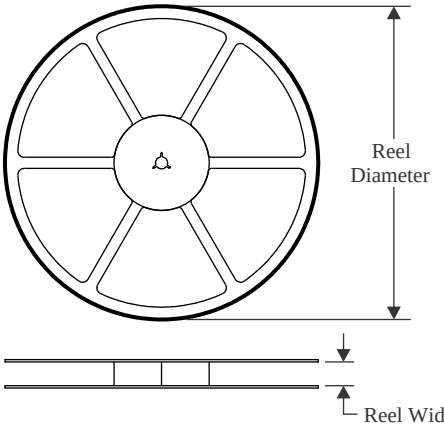
- Catalog : SN74LS33
- Military : SN54LS33

NOTE: Qualified Version Definitions:

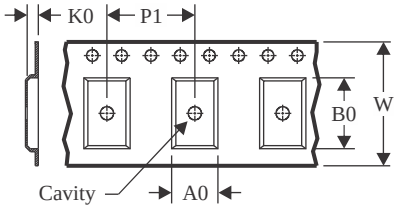
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

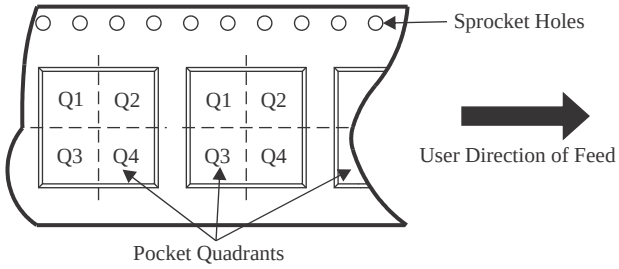


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

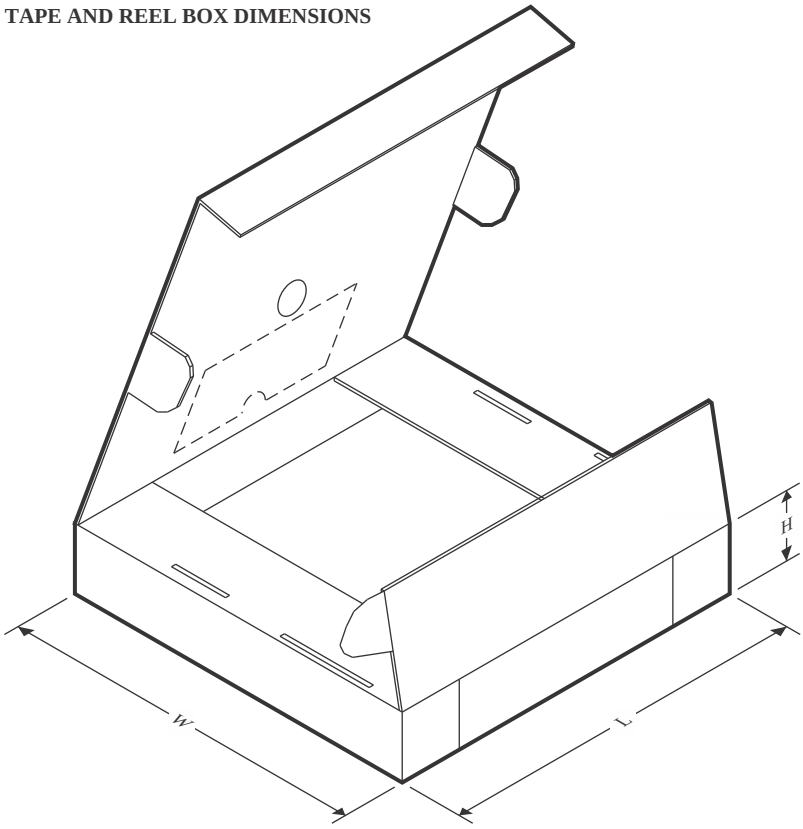
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS33DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS33NSR	SOP	NS	14	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1

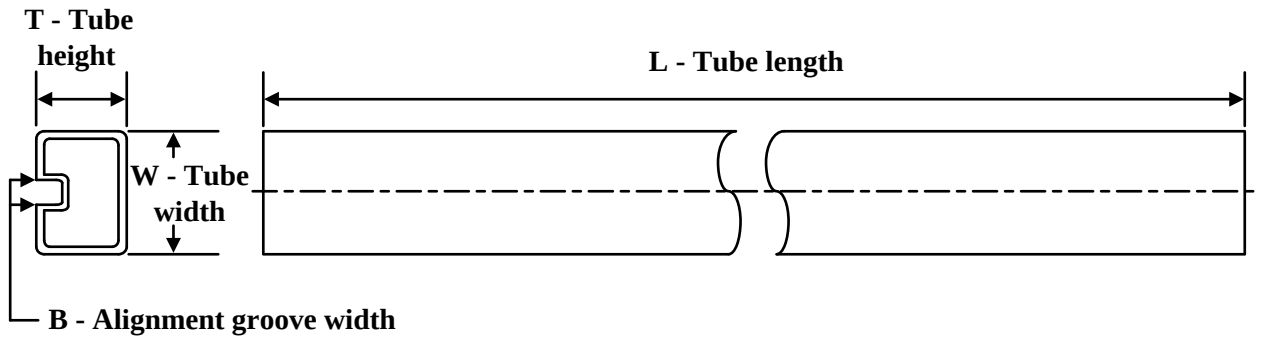
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

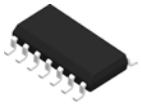
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS33DR	SOIC	D	14	2500	353.0	353.0	32.0
SN74LS33NSR	SOP	NS	14	2000	353.0	353.0	32.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
8512601DA	W	CFP	14	25	506.98	26.16	6220	NA
SN74LS33N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS33N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS33N.A	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS33N.A	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54LS33W	W	CFP	14	25	506.98	26.16	6220	NA
SNJ54LS33W.A	W	CFP	14	25	506.98	26.16	6220	NA

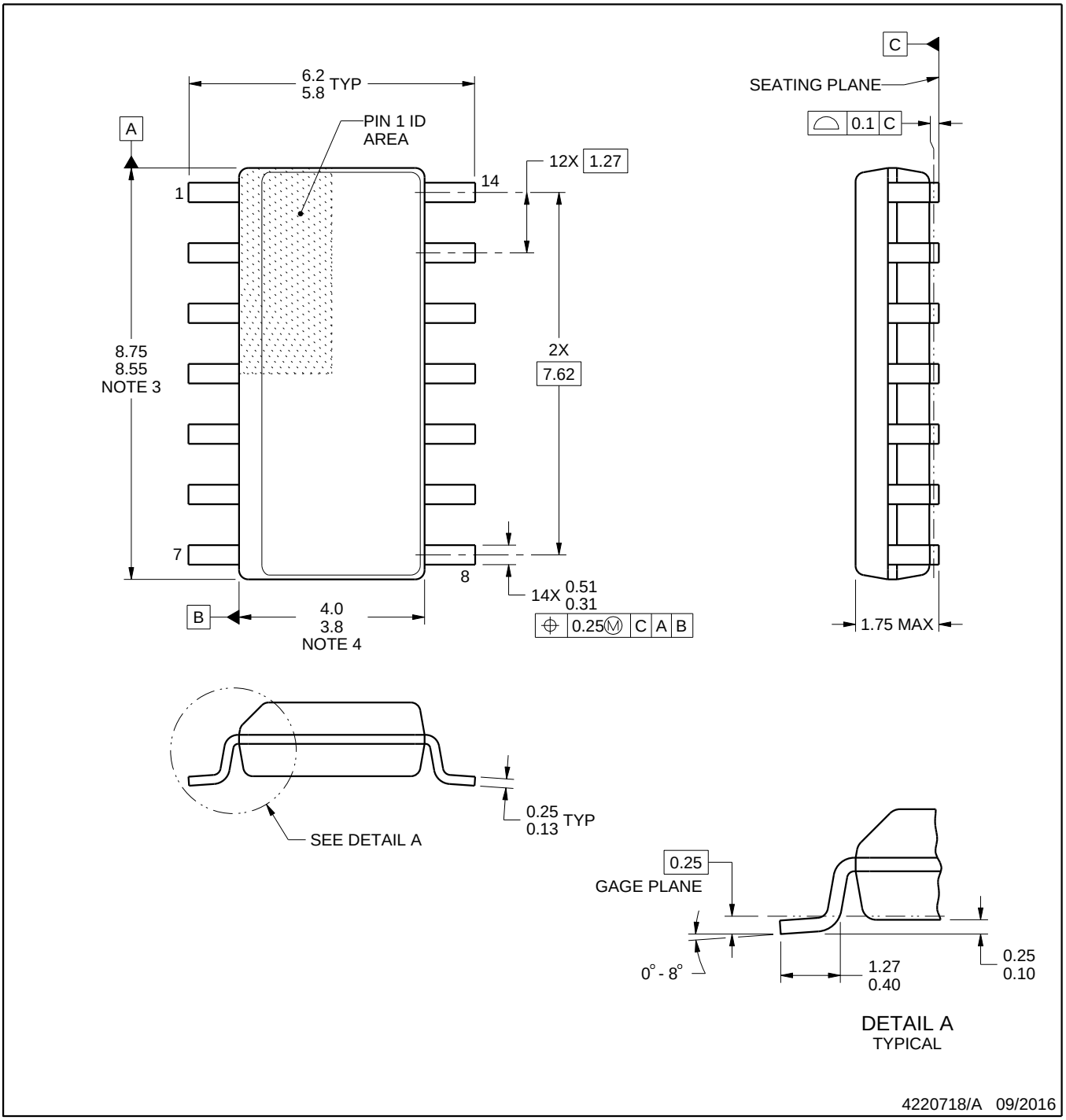


PACKAGE OUTLINE

D0014A

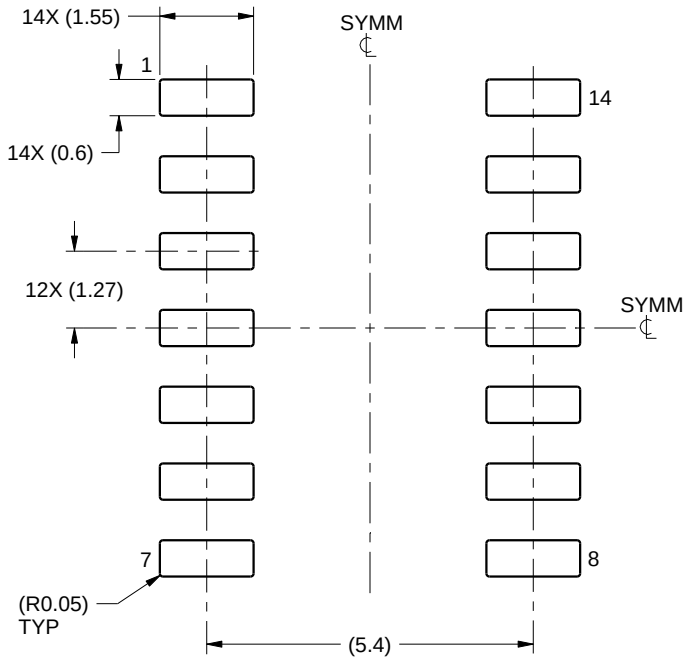
SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

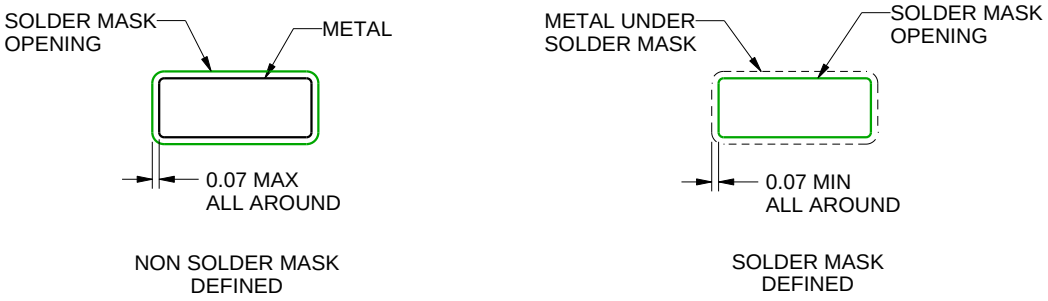


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.



LAND PATTERN EXAMPLE
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

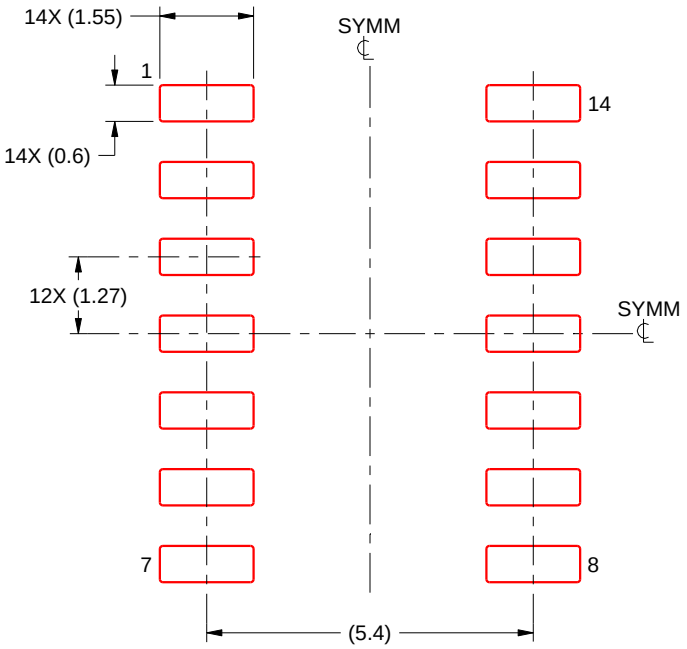
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:8X

4220718/A 09/2016

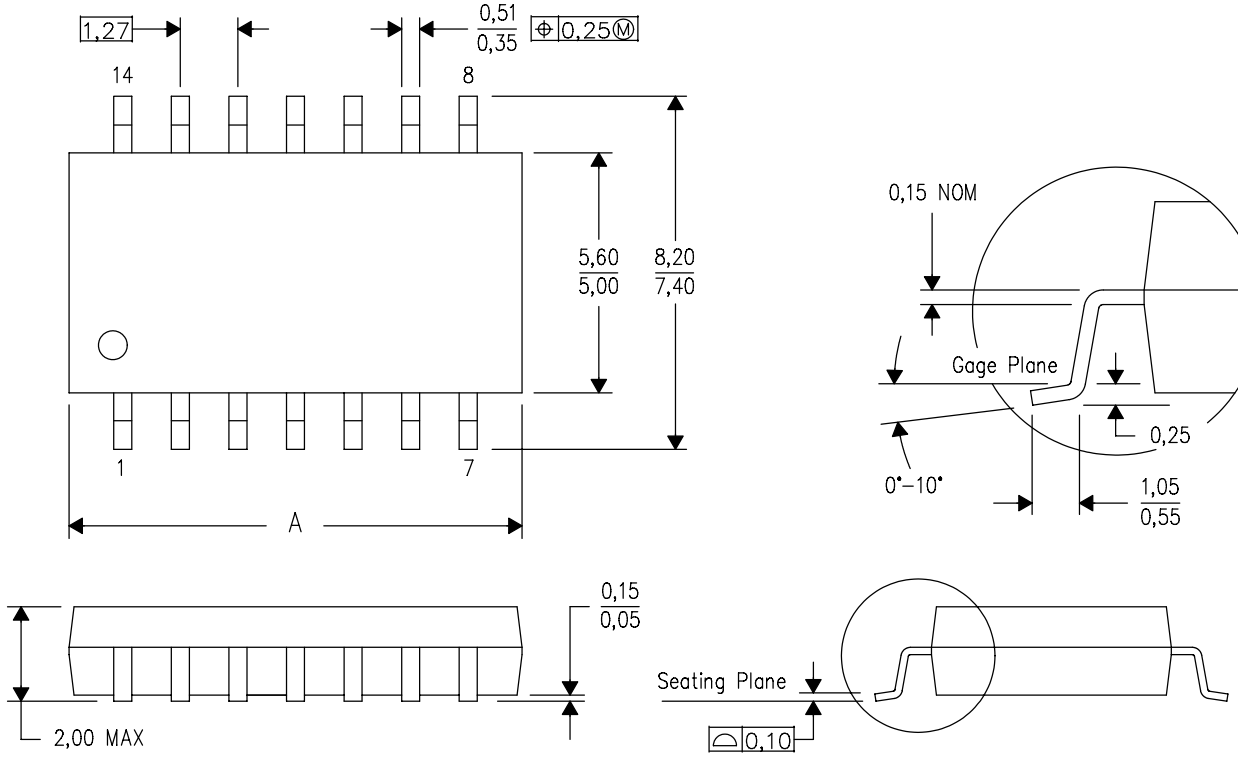
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN

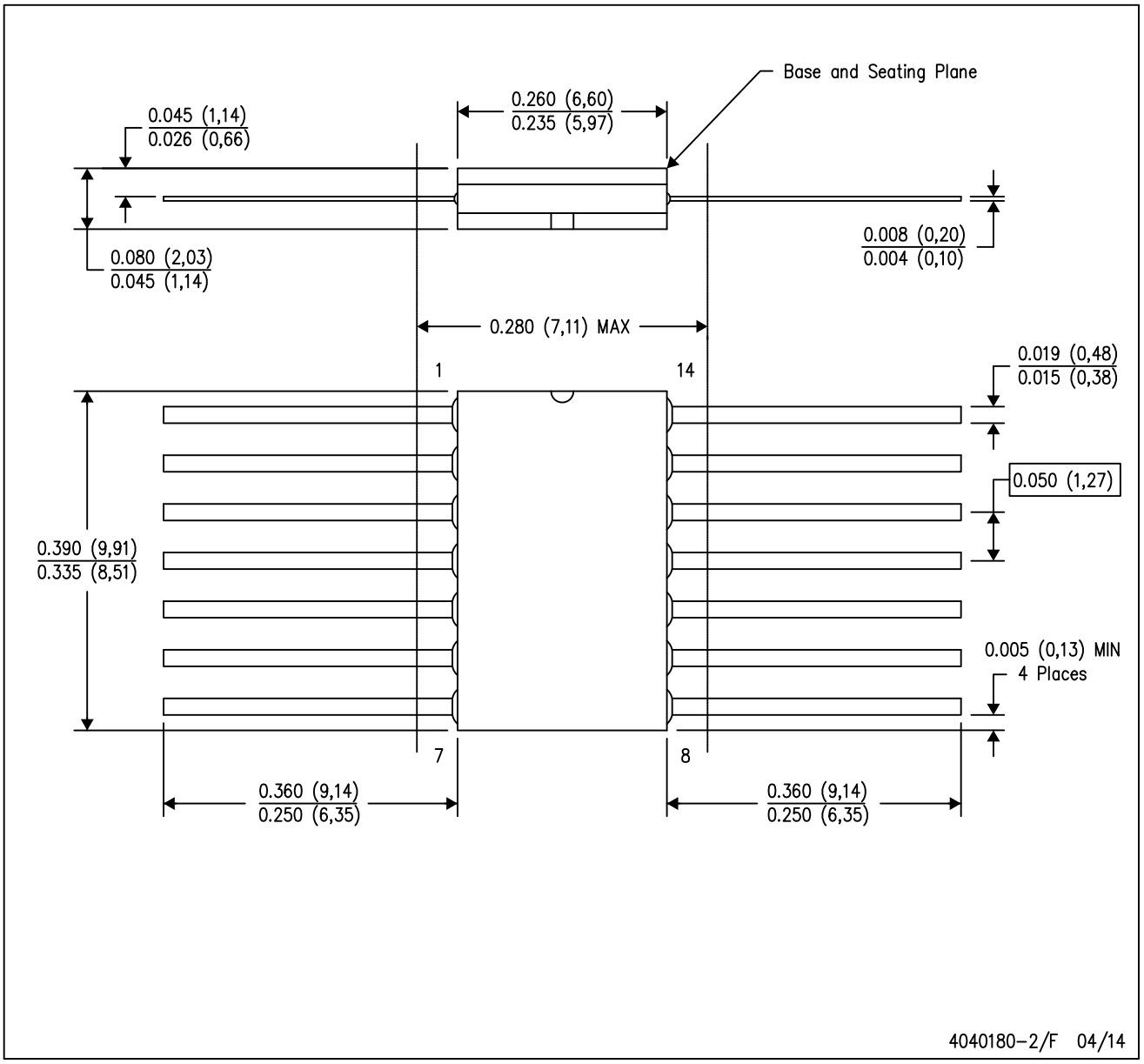


DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

W (R–GDFP–F14) CERAMIC DUAL FLATPACK

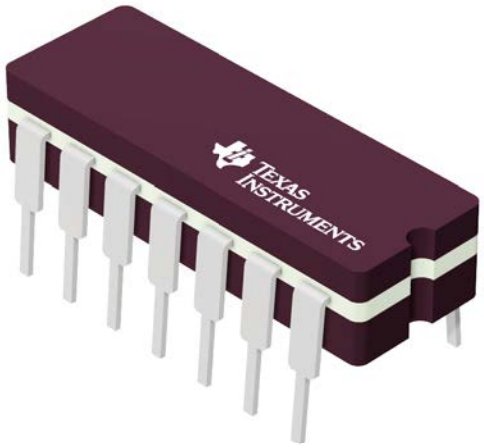


NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP1–F14

GENERIC PACKAGE VIEW

J 14 CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

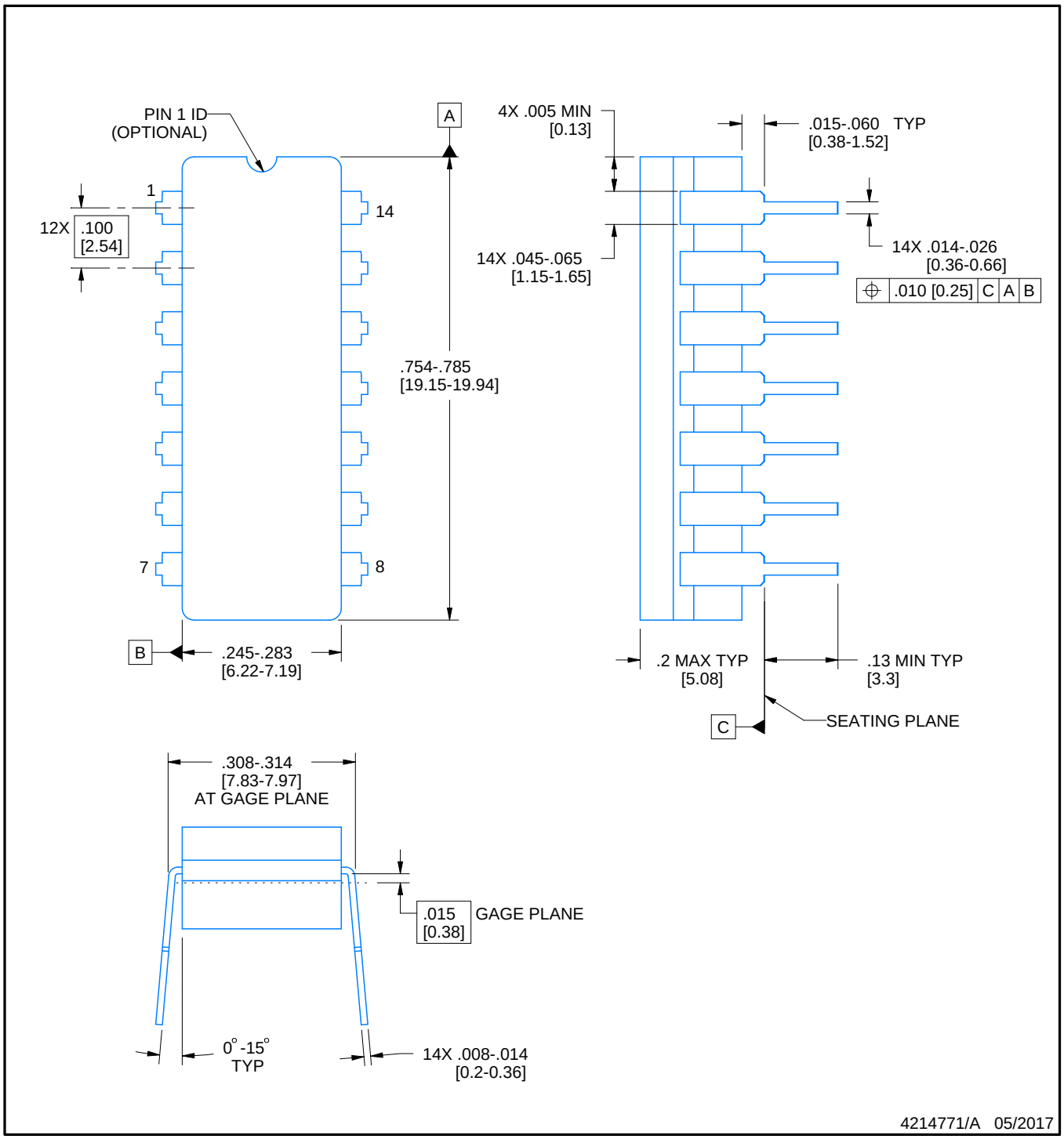
4040083-5/G

PACKAGE OUTLINE

J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



NOTES:

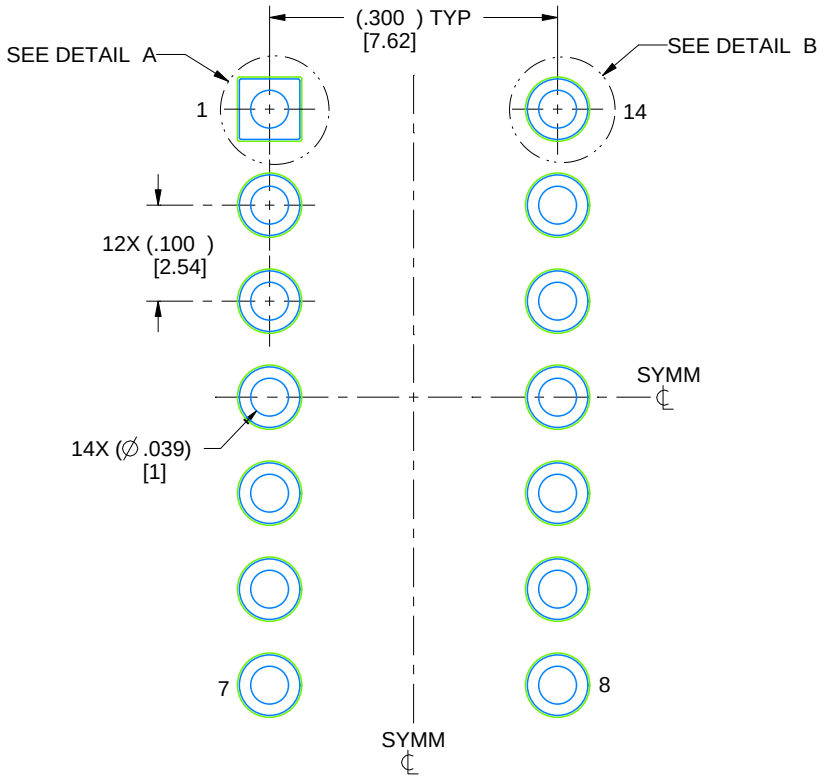
1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermitically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

EXAMPLE BOARD LAYOUT

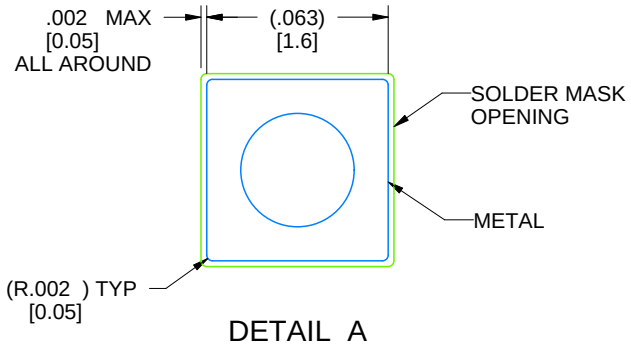
J0014A

CDIP - 5.08 mm max height

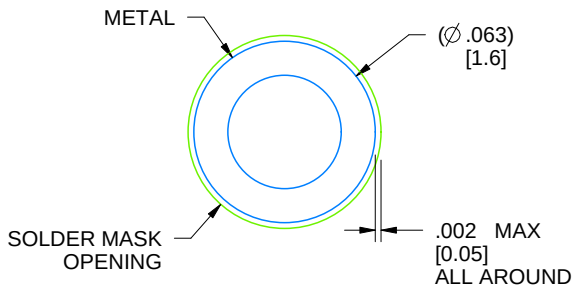
CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE: 5X



DETAIL A
SCALE: 15X



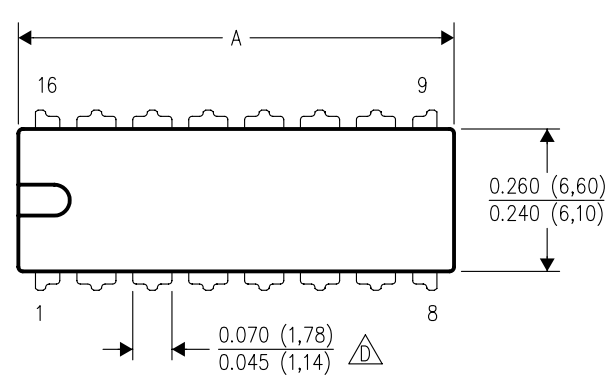
DETAIL B
13X, SCALE: 15X

4214771/A 05/2017

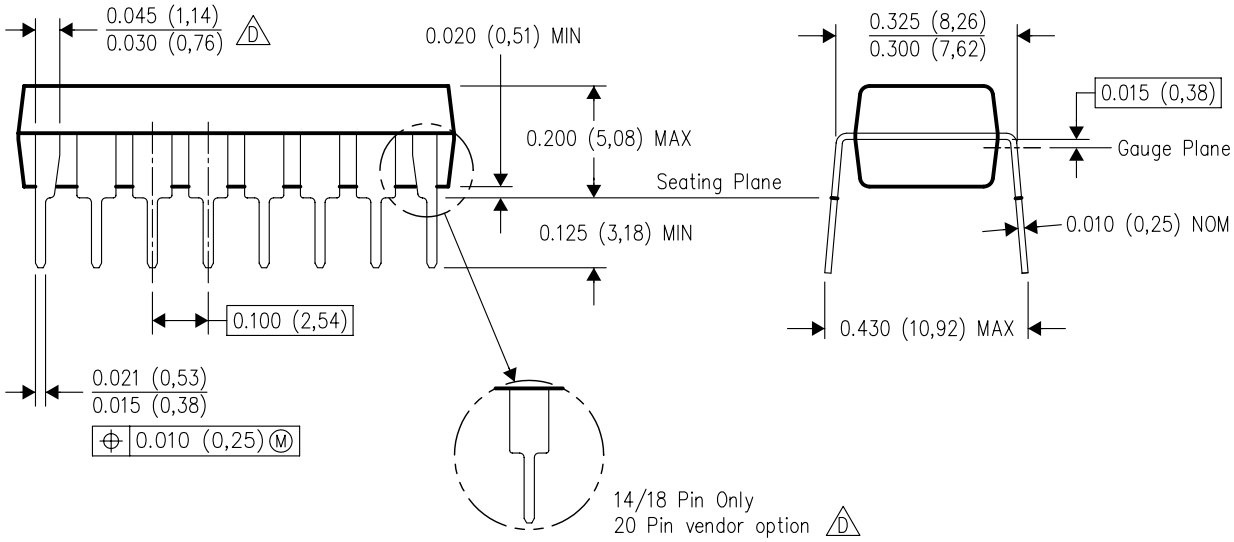
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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